

Fast and Precise Inspection, Powered by Cutting Edge AI Technology



Working together with our customers to create a better manufacturing environment

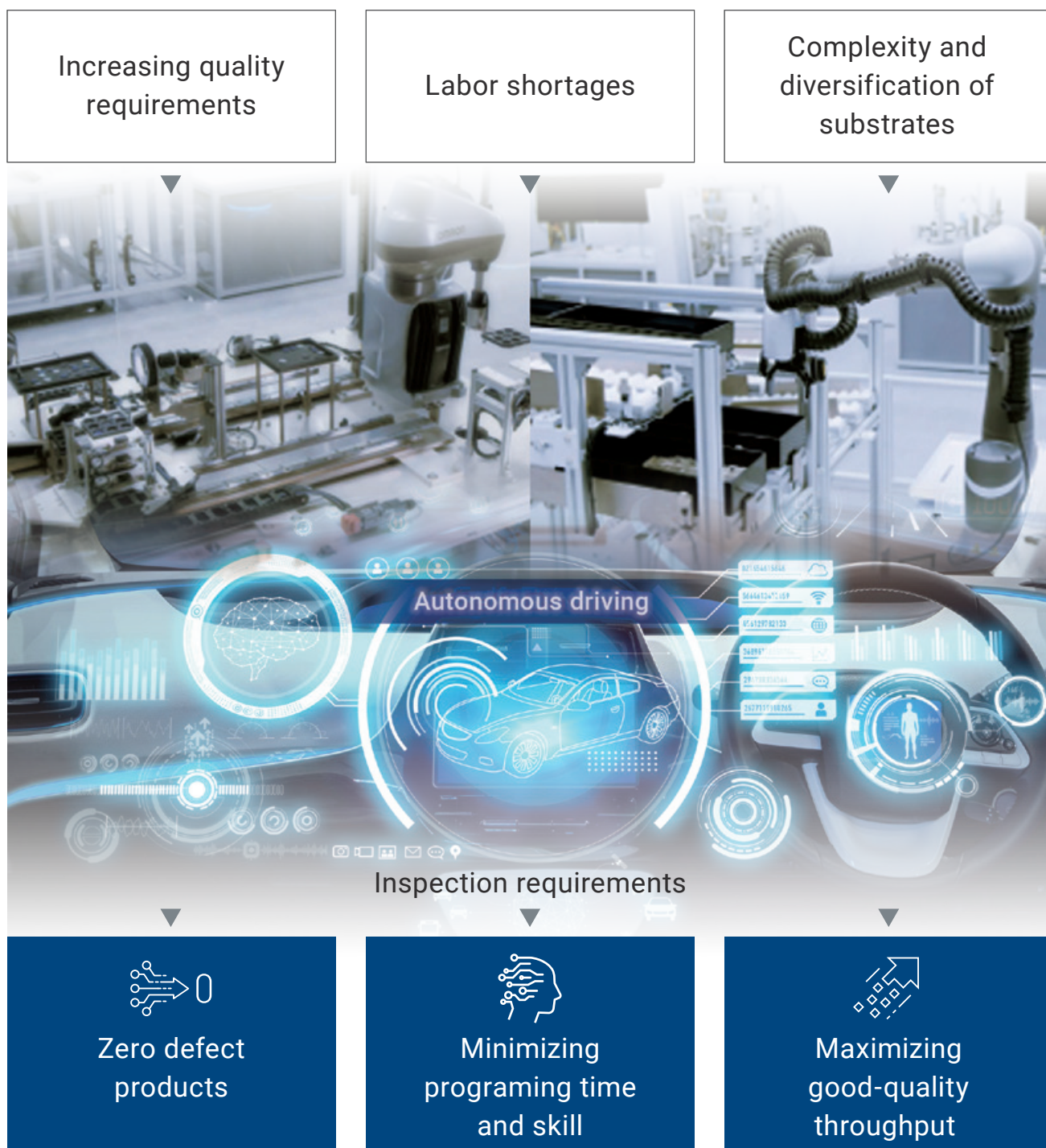
The technological evolution of the market has made manufacturing demands more complex and diverse, with higher quality requirements. In parallel, labor shortages are only adding to these challenges.

There is an urgent need to not only purchase new manufacturing equipment and improve performance, but also develop and train a skilled workforce able to support production.

In order to respond to these trends, Omron Inspection Systems Division is committed to:


- Zero defect products through reliable, high-precision inspection
- Minimizing programming time and skill through AI and quantitative inspection
- Maximizing good-quality throughput to prevent defects through the utilization of accurate quality data from inspection equipment alongside manufacturing data

Trends of manufacturing environment



Omron's unique technology achieves the inspection requirements


Zero overlooking



Imaging technology
MDMC*¹
illumination+MPS*²

High-precision solder
shape restoration
by using AI


Easy operation for best performance



Quantitative
inspection library
based on international
standards


Auto-programming
using AI

Maximizing Good Throughput



M2M*³ system

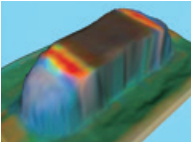
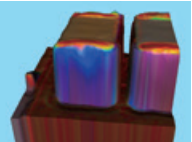
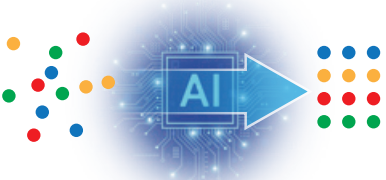
Machine monitoring
and predictive
maintenance



VT-S1080-V3/VT-S1040-V3/VT-Z600-V3

*1. Multi Direction Multi Color
*2. Micro Phase Shift
*3. Machine to Machine

Remove tact time bottlenecks and reduce operator related steps and man-hour related inspections.

Faster	With greater accuracy	More easily
<p>Fastest 7000mm²/sec</p> <p><small>*Resolution 12.5µm</small></p> <p>High-speed inspection</p>	<p>Solder protrusion 0.15mm Chip-to-chip spacing 0.15mm</p> <div style="display: flex; justify-content: space-around;">   </div> <p>High-precision shape restoration</p>	 <p>AI auto-program</p>

Hardware improvements and a new imaging mode enable speed up of approximately 125%*⁴ compared to the conventional type. We have also added a lineup with a resolution of 10µm, which is compatible with high density and miniaturization of components. In addition, AI automatic program has reduced program creation times by approximately 80%*⁵ compared to the previous model.

*4. Comparison with VT-S10-V2 Series
*5. Comparison with manual creation

High-precision solder shape reconstruction helps achieve zero defect products



The combination of Omron's own patented technologies achieves highly robust*6 and reliable inspection performance.

*6: Excellent filtering of noise that effects the judgement of inspection results such as shadows, secondary reflections, abnormal defect shapes and other uncertain factors.

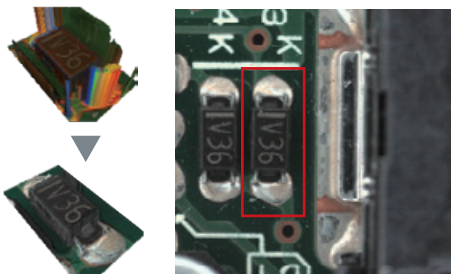
Latest camera technology	Phase shift+ MPS ⁹	MDMC ¹⁰ illumination
<p>CXP-12⁷</p>		
<p>High-speed, high-quality images</p> <p>Equipped with an OMRON in-house camera optimized for inspection. High-definition images with low noise and strong contrast acquired and inspected at high speed. The inspection speed is about 150%⁸ faster than the conventional one.</p> <p>*7: Compared to our VT-S10 series-based verification substrates.</p> <p>*8: CoaXPress 2.0 An interface standard that enables high-speed transmission of large amounts of data.</p>	<p>Phase shift+ MPS</p> <p>Equipped with a proprietary design projector. Automatic control of multiple fringe patterns and light intensity realizes optimal inspection. The effect of secondary reflective is also minimized by use of MPS technology.</p> <p>*9: Micro Phase Shift</p>	<p>Direction lighting + White lighting</p> <p>Equipped with a technique to irradiate multidirectional RGB lights. More high-precision inspection accomplished by capturing variety of shape information even complex fillet shapes. Applied white lighting allows accurate detection and reading of component printing.</p> <p>*10: Multi Direction Multi Color</p>



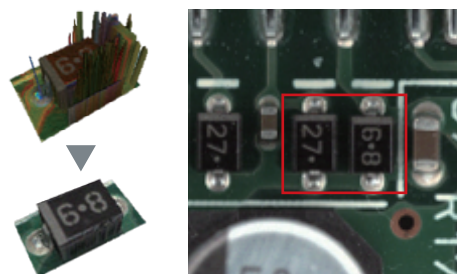
Higher accuracy with AI model generated from huge number of images.



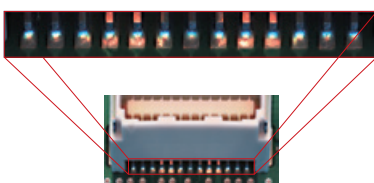
Noise reduction



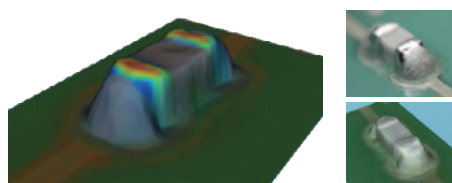
Reduces the effect of shadows due to large parts



Visibility even at the connector solder joint



Stable inspection of microscopic parts



The above images are taken and presented with the permission of a customers from a production board.

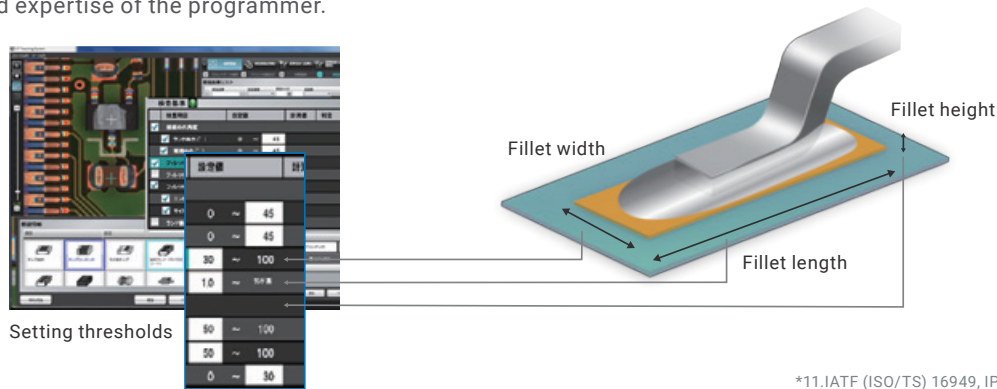
For sample image details Please check here.

Minimization of programming efforts by quantitative inspection and AI-assisted qualitative inspection



Quantative inspection is compliant with international standards*11

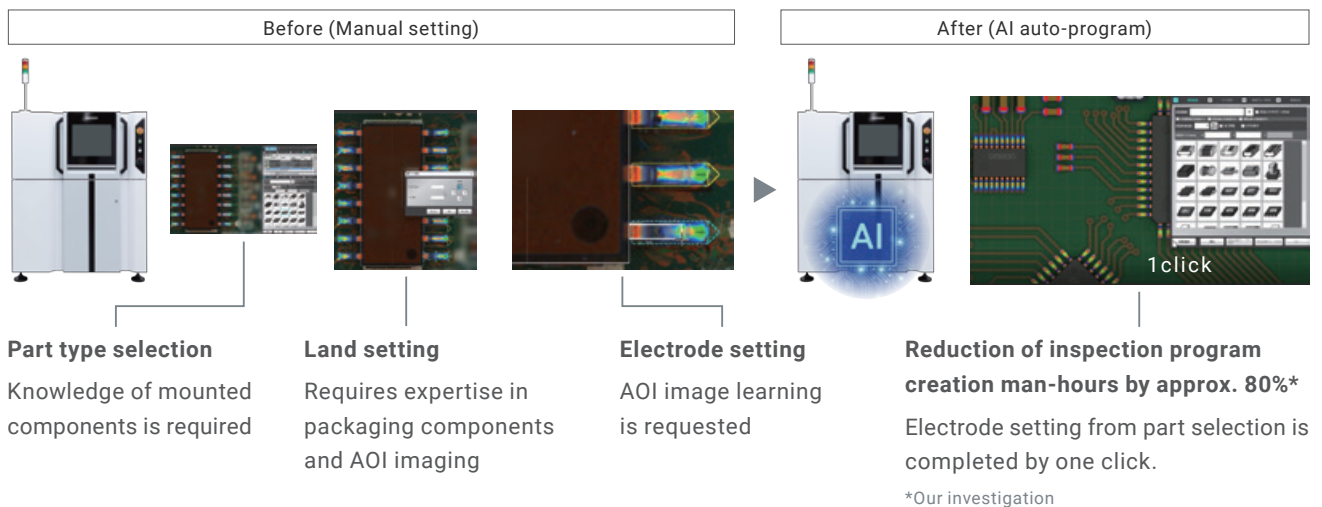
Directly set machine inspection criteria is based on international standards applied as inspection criteria, it doesn't rely on the skill and expertise of the programmer.



*11.IATF (ISO/TS) 16949, IPC quality standards, etc.

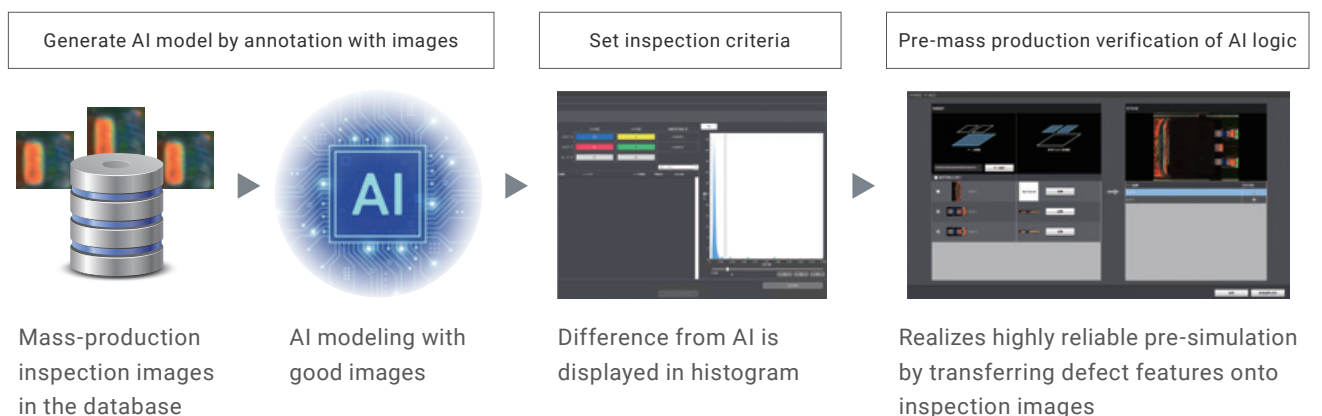
AI auto-program

Component types are determined by AI based on the component shapes on the substrates. Reduces man-hours and skills in initial setting of inspection programs by automating window adjustment and setting of reference values, etc.



AI logic

AI modeling is generated by annotation of good images stored in the server. After confirming the validity of AI model by simulating it, it can be applied to the inspection.

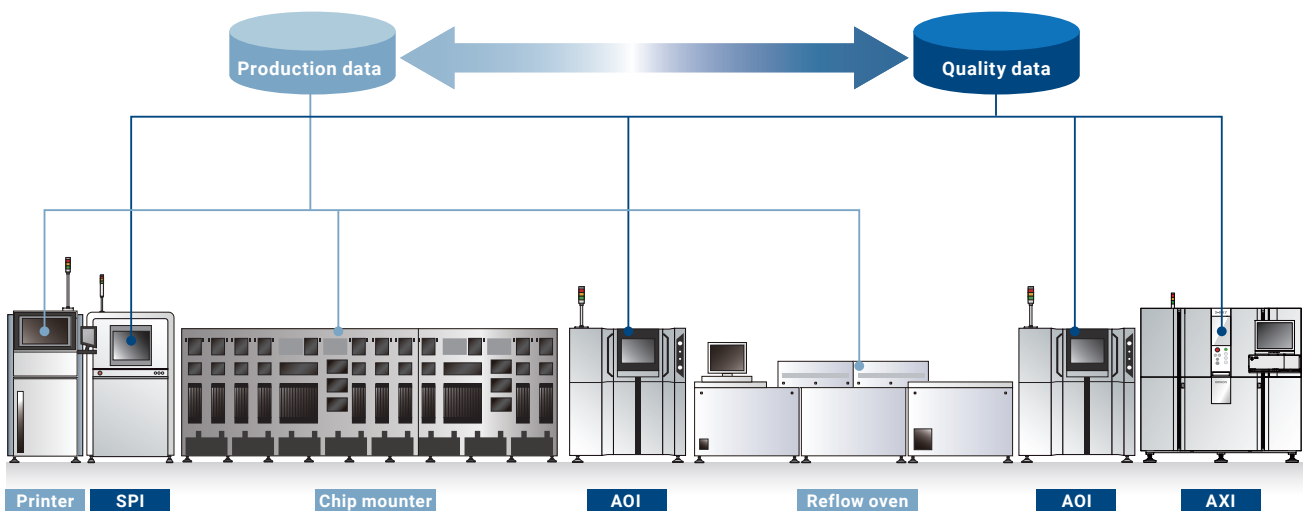


Maximizing good-quality throughput by using quality focused, M2M system

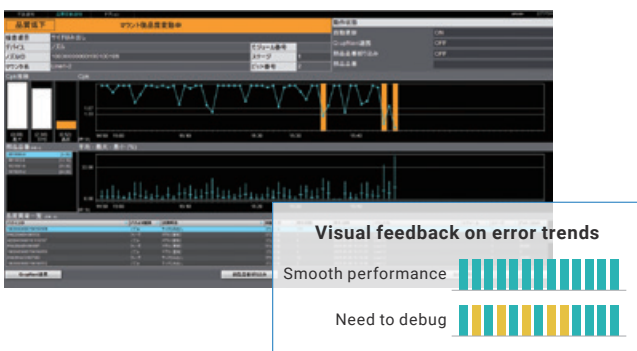


M2M system

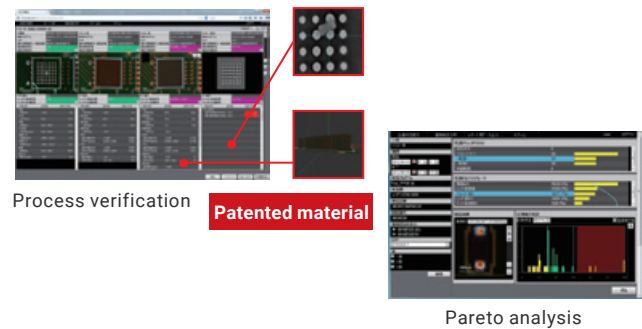
To optimize the quality and equipment operation status without human intervention, made possible by enabling autonomous communication and exchange of information between various connected, production equipment.



Efficiency of inspection process

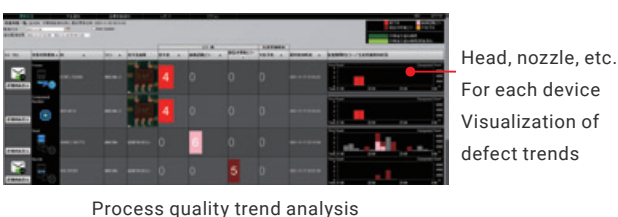


Early identification of factors of defects



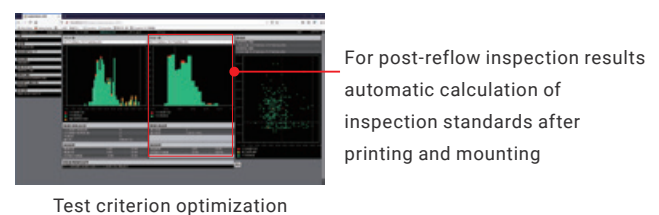
*SPI/AOI/AXI inspection-system cooperation

Prevention of defects



*M2M system requires the license linking to chip mounters.

Improvement of Line Orthogonal Rate



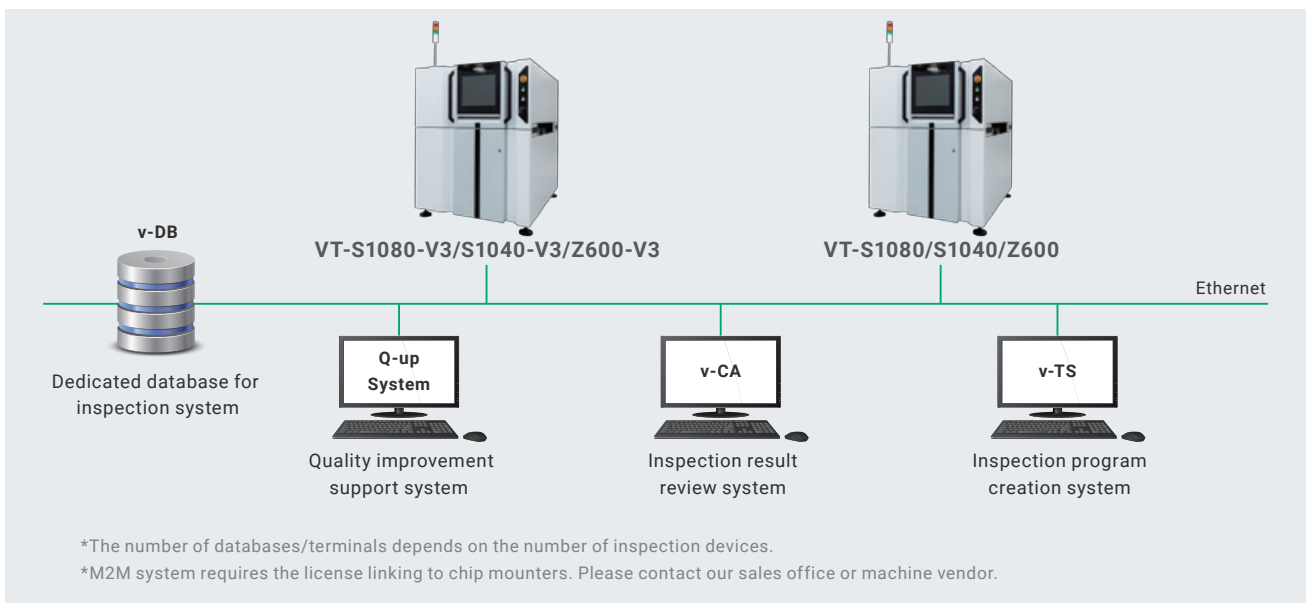
*The license from CKD is required.

Zero down time production line with equipment monitoring and predictive maintenance

Equipped with Omron control hardware technology, this system allows real-time collection of information from all the IoT connected devices inside the inspection equipment. It allows the equipment status to be visualized, enabling predictive maintenance and quality traceability.



System configuration



VT series product line-up

PCB inspection system (AOI)

High-speed CT automated X-Ray inspection system (AXI)



Model: VT-S1080/S1040 /Z600 series



Model: VT-X750

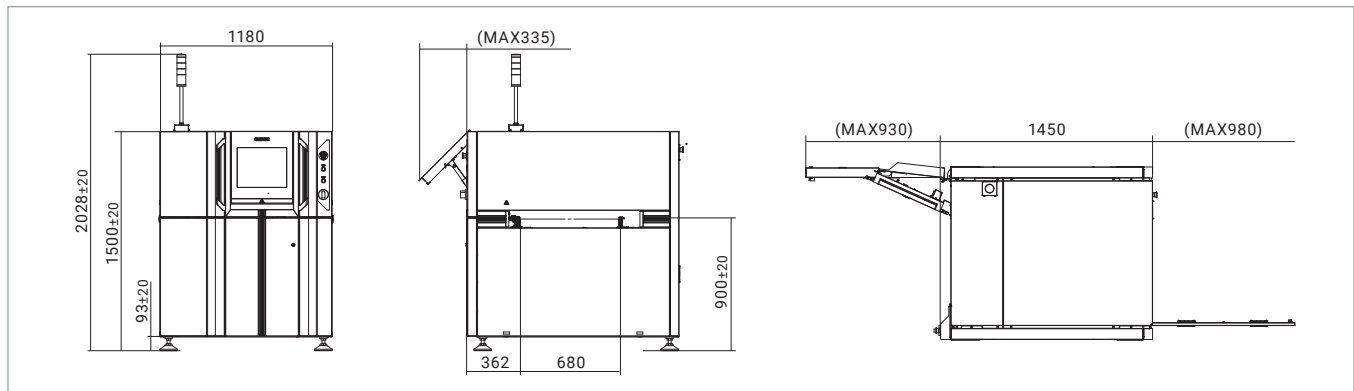


Model: VT-X850



Model: VT-X950

Outline dimensional drawing



Hardware configuration / Functional specifications

Type	VT-S1080-V3-R10	VT-S1040-V3-R10	VT-S1080-V3-R12	VT-S1040-V3-R12	VT-Z600-V3-R12
Outer dimensions	1180(W) × 1450(D) × 1500(H)mm (excluding tower lamp and monitor)				
Weight	Approx. 1240Kg				
Power supply	200 to 240 V AC (Single phase); Voltage fluctuation range ±10% 50/60Hz				
Rated power	2.0 kVA (Maximum current 10 A)				
Line height	900±20mm				
Air supply	Not required				
Operating temperature range	10~35°C				
Operating humidity range	35 to 80% RH (Non-condensing)				
Camera	Direct	25Mpix			
	Oblique	5Mpix	—	5Mpix	—
Resolution	Direct	10µm		12.5µm	
	Oblique	10µm	—	10µm	—
FOV	Direct	51.2 × 51.2mm		52.5 × 52.5mm	
	Oblique	25.9 × 19.4mm	—	25.9 × 19.4mm	—
Inspection principle	Hybrid 3DShape reconstruction MDMC*12 illumination+Phase shift (MPS*13)	Hybrid 3DShape reconstruction MDMC*12 illumination+Phase shift (MPS*13 option)	Hybrid 3DShape reconstruction MDMC*12 illumination+Phase shift (MPS*13)	Hybrid 3DShape reconstruction MDMC*12 illumination+Phase shift (MPS*13 option)	2.5D Shape reconstruction MDMC*12 illumination
Supported PCB size	Size	Single lane: 50(W) × 50(D)~510(W) × 680(D)mm Dual lane: 50(W) × 50(D)~510(W) × 330(D)mm			
	Thickness	0.4~4mm			
	Weight	4Kg			
Clearance	Clearance on PCB: 50mm from board surface Clearance under PCB: 50mm from the back of the board (including PCB warpage, deflection, component tolerance, etc.)				
Height measurement range	25.4mm				—
Inspection item	Component height, lift, tilt, missing or wrong component, wrong polarity, flipped component, OCR inspection, 2D code, component offset (X/Y/rotation), fillet*14 (height/length, end joint width, wetting angle, side joint length), exposed land, foreign material, land error, lead offset, lead posture, lead presence, solder ball, solder bridge, distance between components, component angle				Missing or wrong component, wrong polarity, flipped component, OCR inspection, 2Dcode, component offset (X/Y/rotation), fillet (height/length, end joint width, wetting angle, side joint length)*14, exposed land, foreign material, land error, lead offset, lead posture, lead presence, solder ball, solder bridge, distance between components, component angle

*12. MDMC: Multi Direction/Multi Color *13. MPS: Micro Phase Shift *14. Post-reflow process only

- The application examples described in this brochure are for reference only. Please check the functions and safety of the equipment before using it
- When using in conditions or environments not described in this brochure, or for applications such as nuclear energy control systems, railroad systems, aviation systems, vehicles, combustion systems, medical equipment, amusement machines, safety equipment and others that could present a risk to life or property, Omron assumes no guarantee regarding the products except in the case of special product uses identified by Omron or with special agreement.
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